Silicon P-Channel MOS FET

# HITACHI

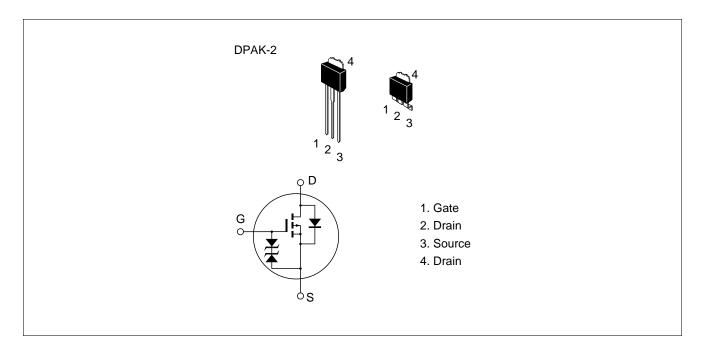
### Application

High speed power switching

#### Features

- Low on-resistance
- Low drive current
- 2.5 V Gate drive device can be driven from 3 V Source
- Suitable for Switching regulator, DC DC converter

#### Outline





## **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit
Drain to source voltage	V <sub>DSS</sub>	-20	V
Gate to source voltage	V <sub>GSS</sub>	±10	V
Drain current	I <sub>D</sub>	-10	А
Drain peak current	L <sub>D(pulse)</sub> *1	-40	А
Body to drain diode reverse drain current	I <sub>DR</sub>	-10	А
Channel dissipation	Pch*2	20	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

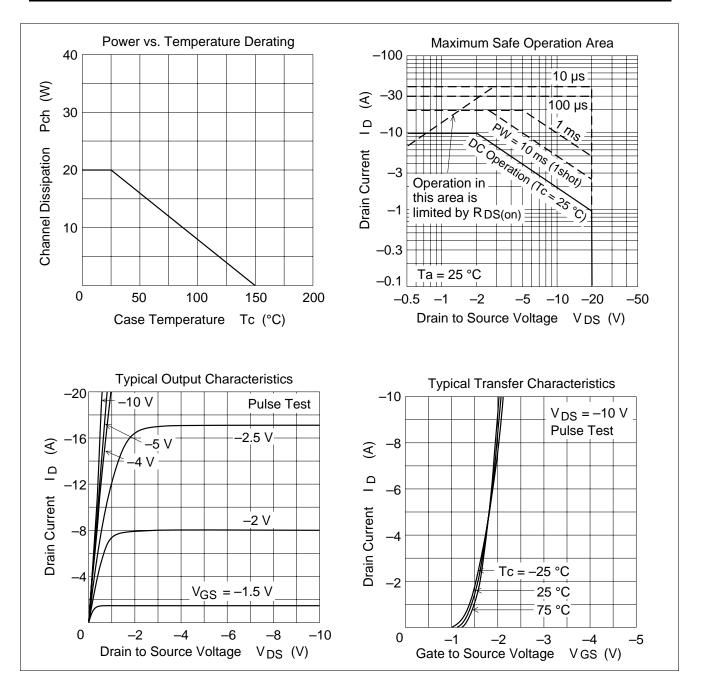
Notes: 1.  $PW \le 10 \ \mu s$ , duty cycle  $\le 1 \ \%$ 

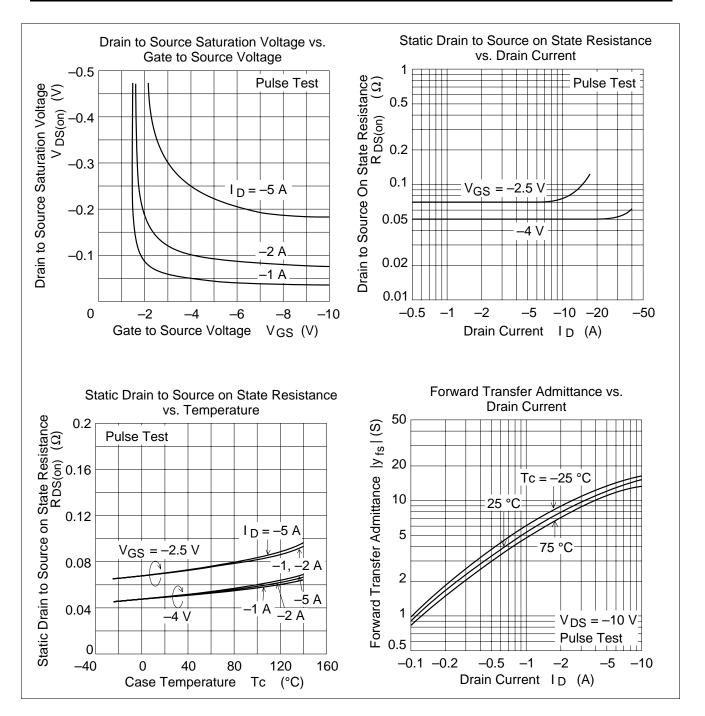
2. Value at Tc = 25°C

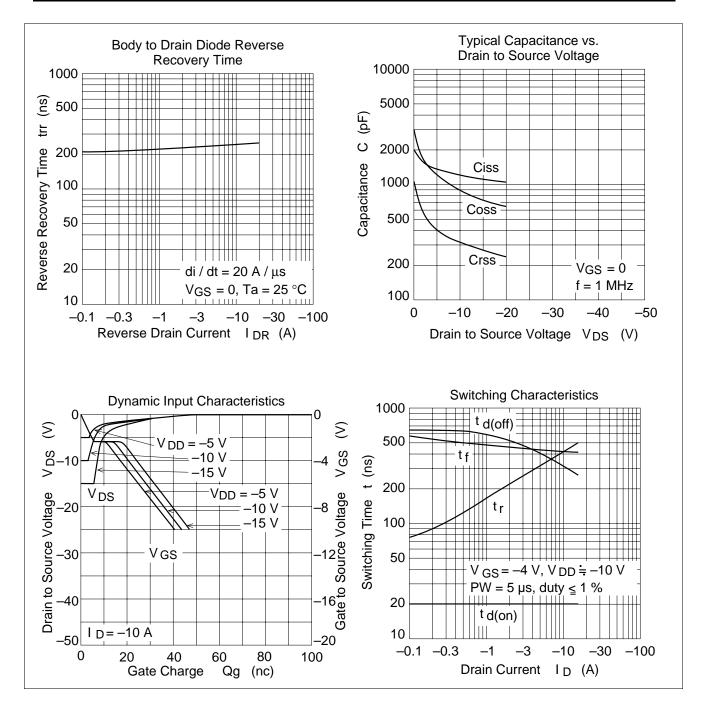
## **Electrical Characteristics** (Ta = 25°C)

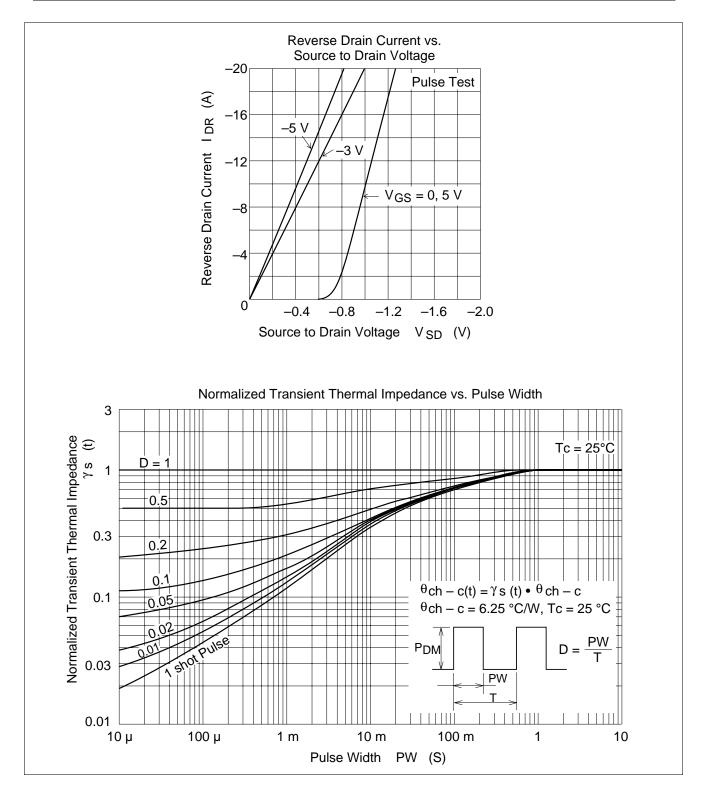
Item	Symbol	Min	Тур	Max	Unit	Test conditions
Drain to source breakdown voltage	$V_{(\text{BR})\text{DSS}}$	-20	_	_	V	$I_{\rm D} = -10$ mA, $V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{(BR)GSS}$	±10	_	_	V	$I_{g} = \pm 200 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I <sub>GSS</sub>		_	±10	μΑ	$V_{GS} = \pm 6.5 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I <sub>DSS</sub>		_	-100	μΑ	$V_{\rm DS} = -16  \rm V,  V_{\rm GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	-0.5	—	-1.5	V	$I_{\rm D} = -1 \text{ mA}, V_{\rm DS} = -10 \text{ V}$
Static drain to source on state resistance	$R_{DS(on)}$	—	0.05	0.07	Ω	$I_{\rm D} = -5 \text{ A}$ $V_{\rm GS} = -4 \text{ V}^{*1}$
		—	0.07	0.1	Ω	$I_{\rm D} = -5 \text{ A}$ $V_{\rm GS} = -2.5 \text{ V}^{*1}$
Forward transfer admittance	y <sub>fs</sub>	7	12	—	S	$I_{D} = -5 \text{ A}$ $V_{DS} = -10 \text{ V}^{*1}$
Input capacitance	Ciss	_	1170	—	pF	$V_{\rm DS} = -10 \ V$
Output capacitance	Coss		860	_	pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	310	—	pF	f = 1 MHz
Turn-on delay time	t <sub>d(on)</sub>		20	_	ns	I <sub>D</sub> = -5 A
Rise time	t,		325	_	ns	$V_{GS} = -4 V$
Turn-off delay time	$t_{d(off)}$		350	_	ns	$R_{L} = 2 \Omega$
Fall time	t <sub>f</sub>	_	425	_	ns	
Body to drain diode forward voltage	$V_{DF}$	—	-1.0	—	V	$I_{\rm F} = -10$ A, $V_{\rm GS} = 0$
Body to drain diode reverse recovery time	t <sub>rr</sub>	_	240	—	ns	$I_F = -10 \text{ A}, V_{GS} = 0,$ diF/dt = 20 A/µs

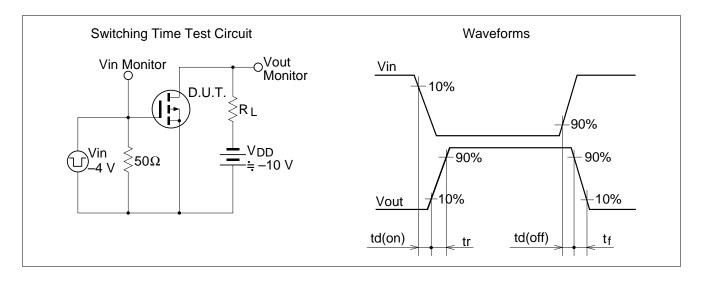
Note: 1. Pulse Test



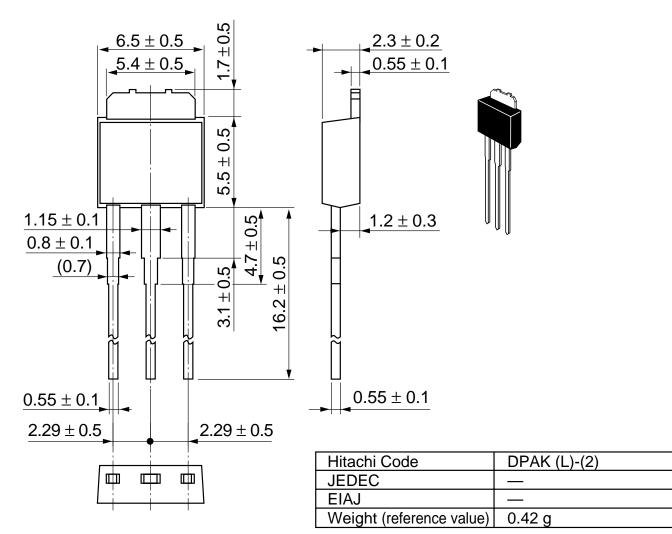








Unit: mm



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